

ABSTRACT OF THE DISCLOSURE

A process for attaching a circuit element such as a capacitor to a substrate includes applying a conductive bonding material to electrical connections of the circuit element and/or substrate; placing the circuit element in position over the substrate; seating the circuit element in the conductive bonding material on the substrate; heating the bonding material to form a conductive bond; and applying a low viscosity wicking material around the area of the circuit element near the substrate. In some embodiments the conductive bonding material is a conductive epoxy such as silver or gold epoxy and the low viscosity wicking material is a flip chip underfill encapsulant.

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